

CLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below hamed in water, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled in:

METHOD FOR REDUCING FREE SURFACE ROUGHNESS OF A SEMICONDUCTOR WAFER

and for which a patent application	on:		(ii	fannlicable)
was filed in the United States	s on as Application No.	(if applicable) (declaration not accompanying application) with		
amendment(s) filed on		(if applicable)		
was filed as PCT internation	al Application No.	on		and was amended
under PCT Article 19 on			_(if applical	ble)
I hereby state that I have reviewamended by any amendment ref	ewed and understand the contererred to above.	nts of the above identified appli	cation, inclu	iding the claims, as
I acknowledge the duty to discle Regulations, § 1.56.	ose information known to me to b	pe material to patentability as def	ined in Title	37, Code of Federal
inventor's certificate listed below	penefits under Title 35, United St w and have also identified below oplication on which priority is cla	any foreign application for pater		
EARLIEST FOREIGN AP	PLICATION(S), IF ANY, FILEI	O PRIOR TO THE FILING DAT	E OF THE A	APPLICATION
APPLICATION NUMBER	COUNTRY	DATE OF FILING (day, month, year)	PRIORITY CLAIMED	
0108859	French	July 4, 2001	☑ YES	□ NO
			☐ YES	□ NO
I hereby claim the benefit under below.	er Title 35, United States Code	, § 119(e) of any United States	provisional	application(s) listed
PROVISIONAL APP	LICATION NUMBER	FILING DATE		
as the subject matter of each of provided by the first paragraph me which is material to patental	r Title 35, United States Code, § the claims of this application is of Title 35, United States Code pility as defined in Title 37, Code action and the national or PCT interests.	not disclosed in the prior United § 112, I acknowledge the duty to e of Federal Regulations, § 1.56 v	States applice of disclose in which became	ation in the manner formation known to
NON-PROVISIONAL	FILING DATE	STA		
APPLICATION NO.			DING	ABANDONED
PCT/FR02/02341	July 4, 2002		X	, , , , , , , , , , , , , , , , , , , ,

^{*} for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

		fto		01/12/0	4
_		SIGNATURE OF INVENTOR 202		DATE	
2	ADDRESS	10 Lotissement le Nivolon	Varces	France	38760
2	POST OFFICE	STREET	CITY	STATE OR COUNTRY	ZIP CODE
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2	INVENTOR	ECARNOT	Ludovic STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	FULL NAME OF	LAST NAME ECADNOT	FIRST NAME	MIDDLE NAME	
1		V	Lamonaura		1
		grat		01/12/04	
		SIGNATURE OF INVENTOR 201		DATE	
1	ADDRESS	2, rue Lesdiguières	Sassenage	France	38360
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	RESIDENCE &	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
2	INVENTOR	NEYRET	Eric		
	FULL NAME OF	LAST NAME	FIRST NAME	MIDDLE NAME	



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Eric NEYRET et al.

Application No.: To be assigned

Group Art Unit:

Filing Date:

Examiner:

For:

METHOD FOR REDUCING FREE SURFACE

Attorney Docket No.: 4717-8300

ROUGHNESS OF A SEMICONDUCTOR

WAFER

POWER OF ATTORNEY BY ASSIGNEE AND EXCLUSION OF INVENTOR(S) UNDER 37 C.F.R. 3.71

Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

The undersigned assignee of the entire interest in the above-identified subject application hereby appoints Allan A. Fanucci (Reg. No. 30,256) and Daniel J. Hulseberg (Reg. No. 36,554) of WINSTON & STRAWN LLP (Customer No. 28765) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Please direct all correspondence for this application to Customer No. 28765 to the attention of Allan A. Fanucci (telephone 212-294-3311, facsimile 212-294-4700).

An assignment of the entire interest in the above-identified subject application is submitted herewith for recording and a copy is attached. The undersigned has reviewed this assignment and, to the best of his knowledge, title is in the assignee seeking to take action in this application and that he is empowered to act on its behalf.

ASSIGNEE:	S.O.J. TEC SILICON ON INSULATOR TECHNOLOGIES S.A.
Signature:	Jue-
Date of Signature:	Jan 12th 2008
Typed Name:	E. HUYGITE
Position/Title:	IP Manager
Address:	Par Technologique des Fontoines
	38126 Crollec CEDEX FRANCE

ASSIGNMENT

WHEREAS, WE,

Eric NEYRET, a citizen of France, residing at 2, rue Lesdiguières, 38360 Sassenage, France; and

Ludovic ECARNOT, a citizen of France, residing at 10 Lotissement le Nivolon, 38760 Varces, France,

ASSIGNORS, are the inventors of the invention entitled: METHOD FOR REDUCING FREE SURFACE ROUGHNESS OF A SEMICONDUCTOR WAFER, for which we have executed an application for a Patent of the United States

\boxtimes	which is identified by Docket No. 4717-8300
	which was filed on as Application No

WHEREAS, S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES, a French corporate body having a place of business at Parc Technologique des Fontaines, F-38190 Bernin, France, ASSIGNEE, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to each inventor in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, each ASSIGNOR has sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, their entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof;

And each ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

And each ASSIGNOR hereby covenants and agrees that they have the full right to convey the entire interest herein assigned, and that they have not executed, and will not execute, any agreement in conflict herewith;

And each ASSIGNOR hereby further covenants and agrees that they will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any

facts known to them respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention;

And each ASSIGNOR hereby authorizes the ASSIGNEE's patent attorney to complete this form by the addition of the application number, application filing date, and attorney docket number, if necessary.

	In witness whe	reof, each inventor	has affixed their signature.	
Date_	Jan 12H	, 200 <u></u>	- E	ric NEYRET
Witne name, and de	who signed the	NEYRET, to m foregoing instrume	e known and known to me to be the nt, and acknowledged the same to be h	person of that his/her free act
			Apled	
				Witness
Date_	Jan 12th	, 200 _4		
-			Ludovio	ECARNOT
that na	On <u>Jomes</u> ss, appeared Luc ame, who signed and deed.	dovic ECARNOT the foregoing ins	, before me, <u>E. HUYGIIE</u> , to me known and known to me to be trument, and acknowledged the same	the person of to be his/her
Date_	Jon 12th	, 200_4	your_	
				Witness